**Product data sheet** 

# 1. General description

Planar passivated high commutation three quadrant triac in a SOT186A "full pack" plastic package intended for use in circuits where high static and dynamic dV/dt and high dl/dt can occur. This "series B" triac will commutate the full rated RMS current at the maximum rated junction temperature without the aid of a snubber.

#### 2. Features and benefits

- · 3Q technology for improved noise immunity
- · High commutation capability with maximum false trigger immunity
- High immunity to false turn-on by dV/dt
- High voltage capability
- · Isolated mounting base package
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

### 3. Applications

- · Electronic thermostats
- High power motor controls e.g washing machines and vacuum cleaners
- · Rectifier-fed DC inductive loads e.g. DC motors and solenoids
- · Refrigeration and air conditioning compressor control

#### 4. Quick reference data

Table 1. Quick reference data

| Symbol                 | Parameter                                | Conditions  |  | Min | Тур | Max | Unit |
|------------------------|--|---|--|-----|-----|-----|------|
| $V_{DRM}$              | repetitive peak off-<br>state voltage    |   |  | -   | -   | 600 | V    |
| I <sub>T(RMS)</sub>    | RMS on-state current                     | full sine wave; $T_h \le 45$ °C; <u>Fig. 1</u> ;<br><u>Fig. 2</u> ; <u>Fig. 3</u>         |  | -   | -   | 16  | А    |
| I <sub>TSM</sub>       | non-repetitive peak on-<br>state current | full sine wave; $T_{j(init)} = 25 \text{ °C}$ ;<br>$t_p = 20 \text{ ms}$ ; Fig. 4; Fig. 5 |  | -   | -   | 140 | А    |
|                        |  | full sine wave; $T_{j(init)}$ = 25 °C;<br>$t_p$ = 16.7 ms                                 |  | -   | -   | 150 | Α    |
| T <sub>j</sub>         | junction temperature                     |   |  | -   | -   | 125 | °C   |
| Static characteristics |  |   |  |     |     |     |      |
| I <sub>GT</sub>        | gate trigger current                     | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G+;$<br>$T_j = 25 \text{ °C}; Fig. 7$       |  | 2   | -   | 50  | mA   |

| Symbol                | Parameter                             | Conditions  | Min  | Тур | Max | Unit |
|-----------------------|---------------------------------------|---|------|-----|-----|------|
|                       |                                       | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ \text{ G-};$<br>$T_j = 25 \text{ °C}; \frac{\text{Fig. 7}}{}$                   | 2    | -   | 50  | mA   |
|                       |                                       | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ T2- G-};$<br>$T_j = 25 \text{ °C}; \frac{\text{Fig. 7}}{}$                   | 2    | -   | 50  | mA   |
| I <sub>H</sub>        | holding current                       | V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>  | -    | -   | 60  | mA   |
| V <sub>T</sub>        | on-state voltage                      | I <sub>T</sub> = 18 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>   | -    | 1.3 | 1.5 | V    |
| Dynamic chara         | acteristics                           |   |      |     |     |      |
| dV <sub>D</sub> /dt   | rate of rise of off-state voltage     | $V_{DM}$ = 402 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit                    | 1000 | -   | -   | V/µs |
| dl <sub>com</sub> /dt | rate of change of commutating current | $V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 16 A; $dV_{com}/dt$ = 20 V/ $\mu$ s; (snubberless condition); gate open circuit | 20   | -   | -   | A/ms |

# 5. Pinning information

**Table 2. Pinning information** 

| Pin | Symbol | Description             | Simplified outline | Graphic symbol |
|-----|--------|-------------------------|--------------------|----------------|
| 1   | T1     | main terminal 1         | mb                 | T2-71          |
| 2   | T2     | main terminal 2         |                    | G<br>sym051    |
| 3   | G      | gate                    |                    | Symosi         |
| mb  | n.c.   | mounting base; isolated |                    |                |
|     |        |                         |                    |                |
|     |        |                         | TO-220F (SOT186A)  |                |

# 6. Ordering information

**Table 3. Ordering information** 

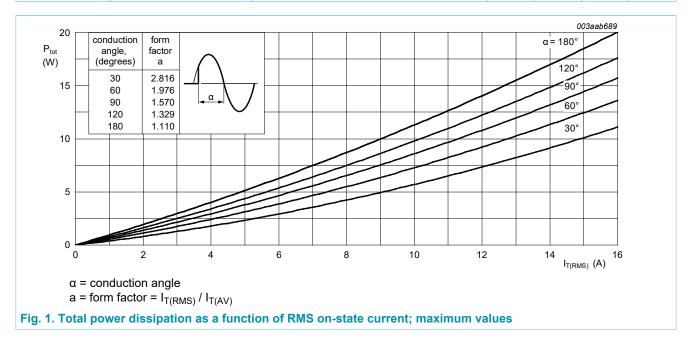
| Type number  | Package |   |         |  |  |
|--------------|---------|---|---------|--|--|
|              | Name    | Description   | Version |  |  |
| BTA316X-600B | TO-220F | plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack" | SOT186A |  |  |

## 7. Limiting values

### **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol              | Parameter                                | Conditions   | Min | Max | Unit |
|---------------------|--|--|-----|-----|------|
| $V_{DRM}$           | repetitive peak off-state voltage        |  | -   | 600 | V    |
| I <sub>T(RMS)</sub> | RMS on-state current                     | full sine wave; $T_h \le 45$ °C; <u>Fig. 1</u> ; <u>Fig. 2</u> ; <u>Fig. 3</u> | -   | 16  | Α    |
| I <sub>TSM</sub>    | non-repetitive peak on-<br>state current | full sine wave; $T_{j(init)} = 25$ °C; $t_p = 20$ ms; Fig. 4; Fig. 5           | -   | 140 | Α    |
|                     |  | full sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 16.7 ms         | -   | 150 | Α    |
| l <sup>2</sup> t    | I <sup>2</sup> t for fusing              | t <sub>p</sub> = 10 ms; SIN  | -   | 98  | A²s  |
| dl <sub>T</sub> /dt | rate of rise of on-state current         | I <sub>G</sub> = 0.2 A   | -   | 100 | A/µs |
| I <sub>GM</sub>     | peak gate current                        |  | -   | 2   | А    |
| $P_{G(AV)}$         | average gate power                       | over any 20 ms period  | -   | 0.5 | W    |
| T <sub>stg</sub>    | storage temperature                      |  | -40 | 150 | °C   |
| Tj                  | junction temperature                     |  | -   | 125 | °C   |



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**3Q Hi-Com Triac** 

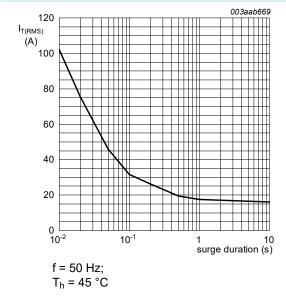


Fig. 2. RMS on-state current as a function of surge duration; maximum values

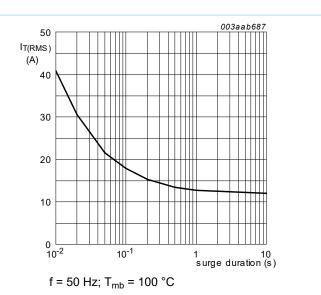


Fig. 3. RMS on-state current as a function of surge duration; maximum values

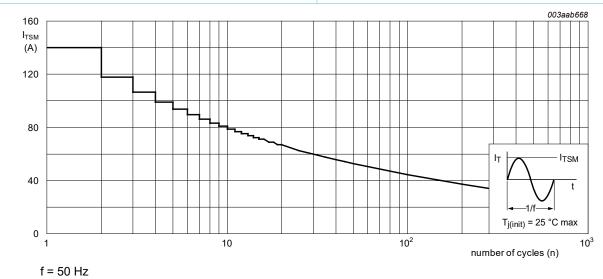
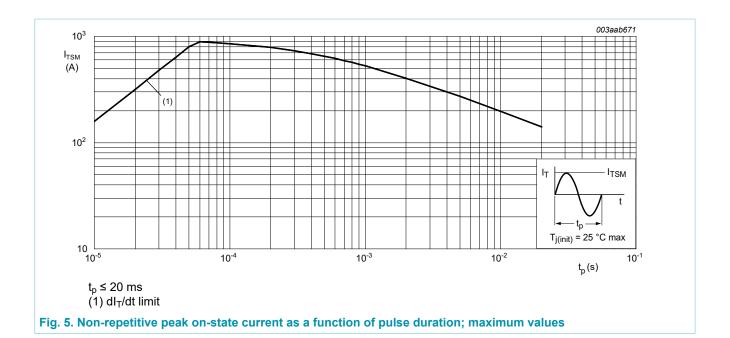


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

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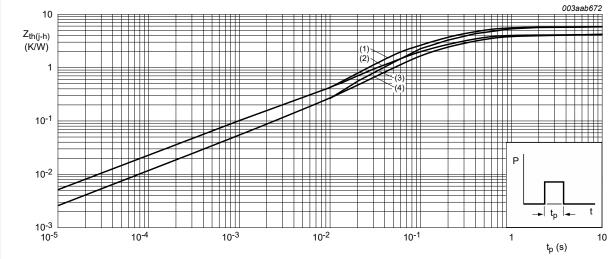
**3Q Hi-Com Triac** 



### 8. Thermal characteristics

**Table 5. Thermal characteristics** 

| Symbol               | Parameter  | Conditions  | Min | Тур | Max | Unit |
|----------------------|--|---|-----|-----|-----|------|
| R <sub>th(j-h)</sub> | thermal resistance from junction to                        | full cycle or half cycle; with heatsink compound; Fig. 6    | -   | -   | 4   | K/W  |
|                      | heatsink   | full cycle or half cycle; without heatsink compound; Fig. 6 | -   | -   | 5.5 | K/W  |
| R <sub>th(j-a)</sub> | thermal resistance<br>from junction to<br>ambient free air | in free air   | _   | 55  | -   | K/W  |



- (1) Unidirectional (half cycle) without heatsink compound
- (2) Unidirectional (half cycle) with heatsink compound
- (3) Bidirectional (full cycle) without heatsink compound
- (4) Bidirectional (full cycle) with heatsink compound

Fig. 6. Transient thermal impedance from junction to heatsink as a function of pulse duration

#### 9. Isolation characteristics

**Table 6. Isolation characteristics** 

| Symbol                 | Parameter             | Conditions  | Min | Тур | Max  | Unit |
|------------------------|-----------------------|---|-----|-----|------|------|
| V <sub>isol(RMS)</sub> | RMS isolation voltage | from all terminals to external heatsink; sinusoidal waveform; clean and dust free; $50 \text{ Hz} \le f \le 60 \text{ Hz}$ ; $RH \le 65 \%$ ; $T_h = 25 ^{\circ}\text{C}$ | -   | -   | 2500 | V    |
| C <sub>isol</sub>      | isolation capacitance | from main terminal 2 to external heatsink; f = 1 MHz; T <sub>h</sub> = 25 °C  | -   | 10  | -    | pF   |

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### 10. Characteristics

#### **Table 7. Characteristics**

| Symbol                | Parameter                             | Conditions  | Min  | Тур | Max | Unit |
|-----------------------|---------------------------------------|---|------|-----|-----|------|
| Static char           | acteristics                           |   | '    |     |     |      |
| I <sub>GT</sub>       | gate trigger current                  | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G+;$<br>$T_j = 25 \text{ °C}; Fig. 7$                                     | 2    | -   | 50  | mA   |
|                       |                                       | $V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$<br>$T_j = 25 \text{ °C; } Fig. 7$                                 | 2    | -   | 50  | mA   |
|                       |                                       | $V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-;}$<br>$T_j = 25 \text{ °C; } Fig. 7$                                   | 2    | -   | 50  | mA   |
| IL                    | latching current                      | $V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T2+ G+;$<br>$T_j = 25 \text{ °C}; Fig. 8$                                     | -    | -   | 60  | mA   |
|                       |                                       | $V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T2+ G-;$<br>$T_j = 25 \text{ °C}; Fig. 8$                                     | -    | -   | 90  | mA   |
|                       |                                       | $V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{ T2- G-};$<br>$T_j = 25 ^{\circ}\text{C}; \text{ Fig. 8}$               | -    | -   | 60  | mA   |
| I <sub>H</sub>        | holding current                       | V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>  | -    | -   | 60  | mA   |
| V <sub>T</sub>        | on-state voltage                      | I <sub>T</sub> = 18 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>   | -    | 1.3 | 1.5 | V    |
| $V_{GT}$              | gate trigger voltage                  | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$<br>Fig. 11  | -    | 0.8 | 1   | V    |
|                       |                                       | $V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 125 \text{ °C};$<br>Fig. 11  | 0.25 | 0.4 | -   | V    |
| I <sub>D</sub>        | off-state current                     | V <sub>D</sub> = 600 V; T <sub>j</sub> = 125 °C   | -    | 0.1 | 0.5 | mA   |
| Dynamic cl            | naracteristics                        |   | '    | -   |     | ,    |
| dV <sub>D</sub> /dt   | rate of rise of off-state voltage     | $V_{DM}$ = 402 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit              | 1000 | -   | -   | V/µs |
| dl <sub>com</sub> /dt | rate of change of commutating current | $V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 16 A; $dV_{com}/dt$ = 20 V/µs; (snubberless condition); gate open circuit | 20   | -   | -   | A/ms |

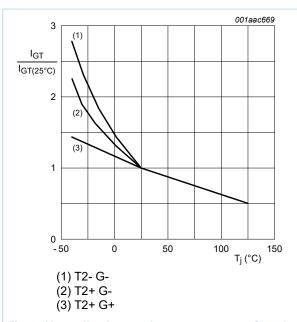


Fig. 7. Normalized gate trigger current as a function of junction temperature

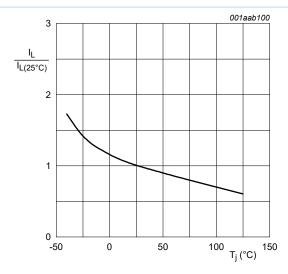


Fig. 8. Normalized latching current as a function of junction temperature

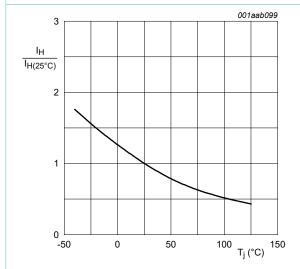
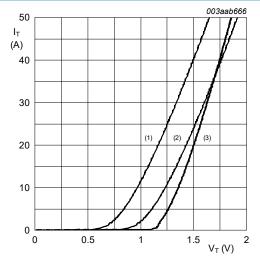


Fig. 9. Normalized holding current as a function of junction temperature



 $V_o$  = 1.024 V;  $R_s$  = 0.021  $\Omega$ 

(1)  $T_j = 125$  °C; typical values (2)  $T_j = 125$  °C; maximum values (3)  $T_j = 25$  °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

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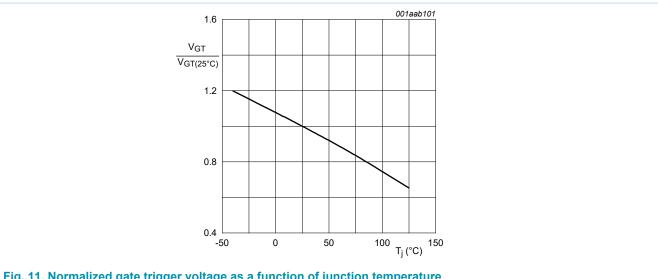


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

## 11. Package outline

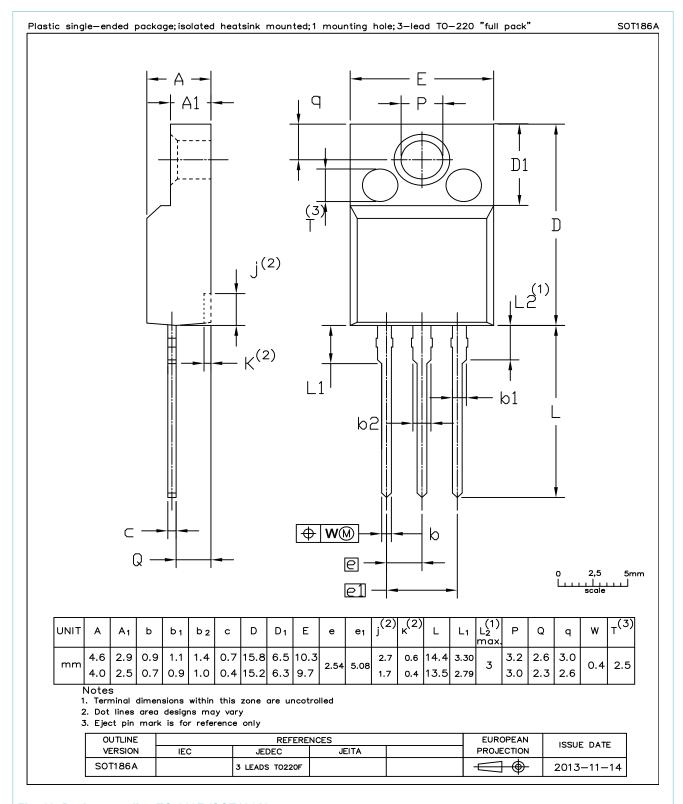


Fig. 12. Package outline TO-220F (SOT186A)

## 12. Legal information

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| Document status [1][2]               | Product status [3] | Definition  |
|--------------------------------------|--------------------|---|
| Objective<br>[short] data<br>sheet   | Development        | This document contains data from the objective specification for product development. |
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